

# SOT1088-1

plastic thermal enhanced ball grid array package; 520 balls;  
heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA520
<b>Package type industry code</b>	HBGA520
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	3-6-2008

Table 1. Package summary

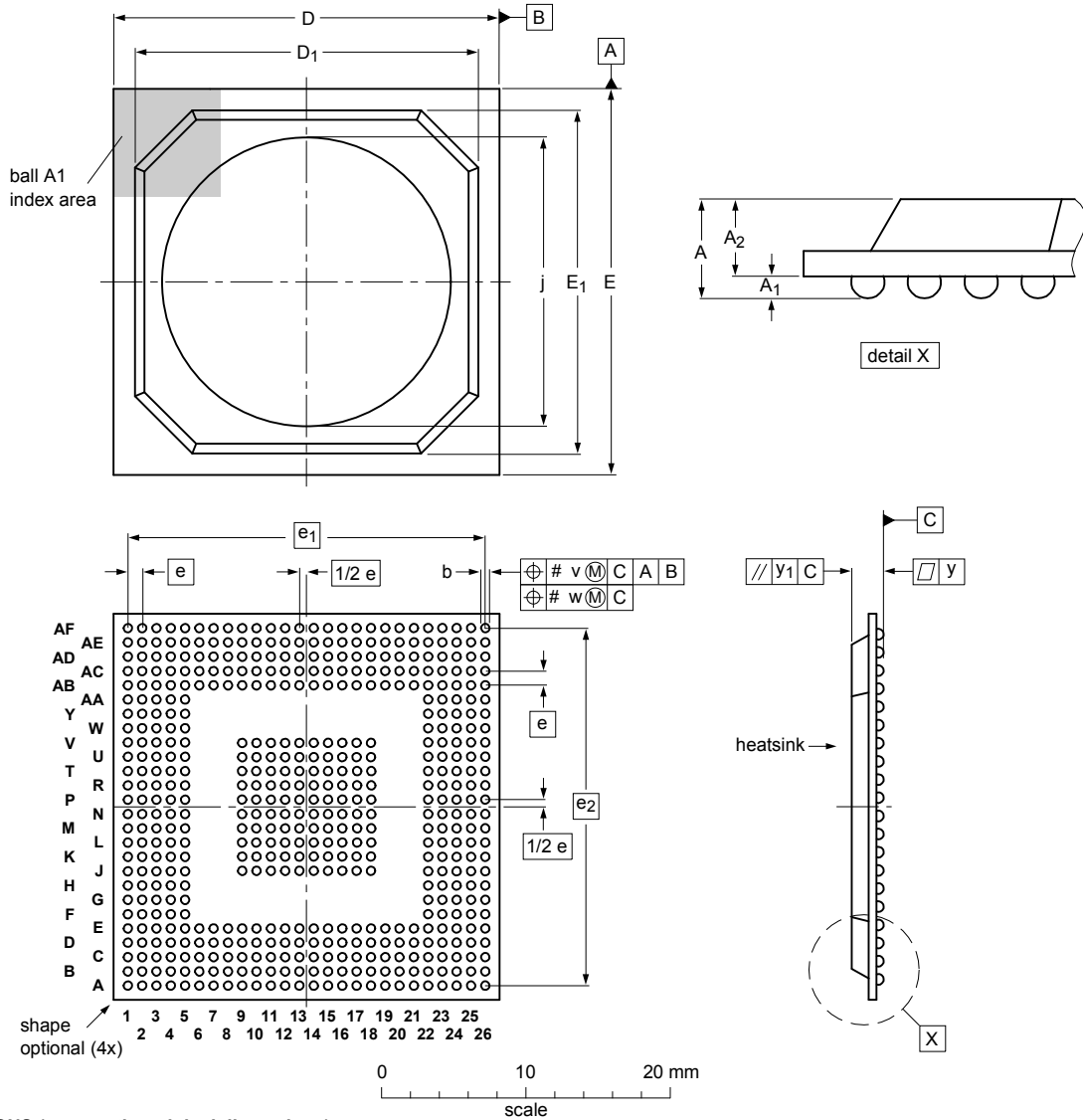
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	2	-	2.25	2.45	mm
A <sub>2</sub>	package height	1.6	-	1.75	1.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	520	-	



2. Package outline

HBGA520: plastic thermal enhanced ball grid array package; 520 balls; heatsink

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DIMENSIONS (mm are the original dimensions)

UNIT		A	A <sub>1</sub>	A <sub>2</sub>	b	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	j	v	w	y	y <sub>1</sub>
mm	max	2.45	0.6	1.85	0.7	27.2	24.75	27.2	24.75		25	25	21.0	0.25	0.1	0.2	0.35
	nom	2.25	0.5	1.75	0.6	27.0	24.00	27.0	24.00	1			20.5				
	min	2.00	0.4	1.60	0.5	26.8	23.75	26.8	23.75				20.0				

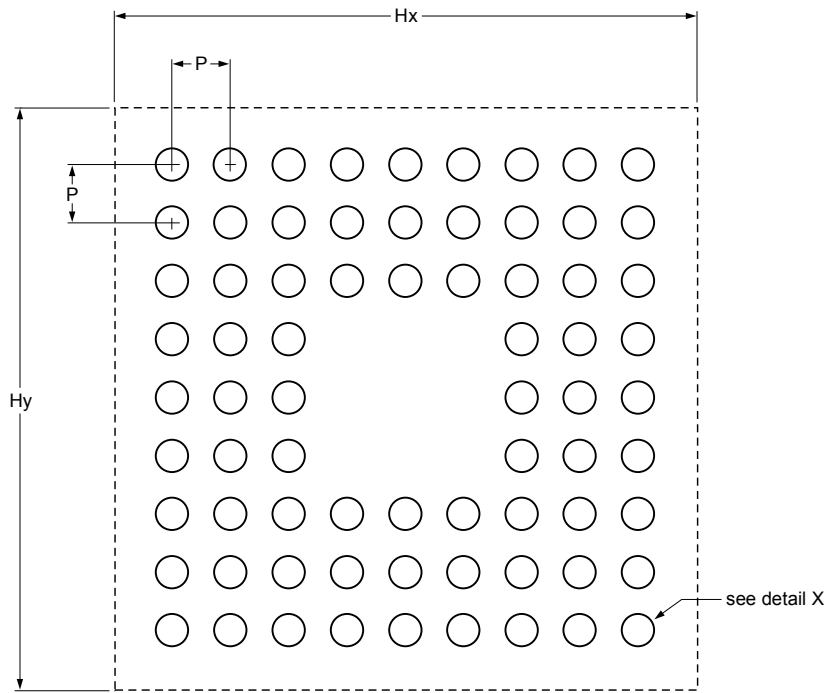
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT1088-1	144E	MS-034	---		08-05-16 08-06-03

Fig. 1. Package outline HBGA520 (SOT1088-1)

### 3. Soldering

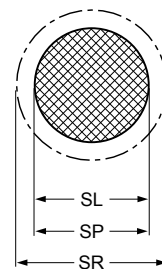
Footprint information for reflow soldering of HBGA520 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- \_\_\_\_\_ solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.00	0.450	0.450	0.600	27.500	27.500

sot1088-1\_fr

Fig. 2. Reflow soldering footprint for HBGA520 (SOT1088-1)

## 4. Legal information

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Date of release: 8 February 2016

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